

IN THE DRAWINGS:

The attached sheets of drawings includes changes to Fig. 5 and Fig. 7. These sheets, which include Figs. 1-11B, replace the original sheets including Figs. 1-11B. In Fig. 5, reference numeral reference numeral "152" has been changed to "176," reference number "176" has been changed to "152," and reference numeral "200" has been changed to "213." In Fig. 7, reference numeral "48" has been changed to "748," and reference numeral "717" has been changed to "747." Also in Fig. 5, the position of reference numeral "756" has been moved, and reference numerals "750," "761," and "762: have been added.

Attachment: Replacement Sheet
Annotated Sheet Showing Changes



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ANNOTATED SHEET SHOWING CHANGES
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10/043,561
JANUARY 8, 2002
APPLIED MATERIALS, INC.
SYSTEM FOR PLANARIZING METAL CONDUCTIVE LAYERS
OLGADO, ET AL.

CONFIRMATION: 7947

FIGURE 5

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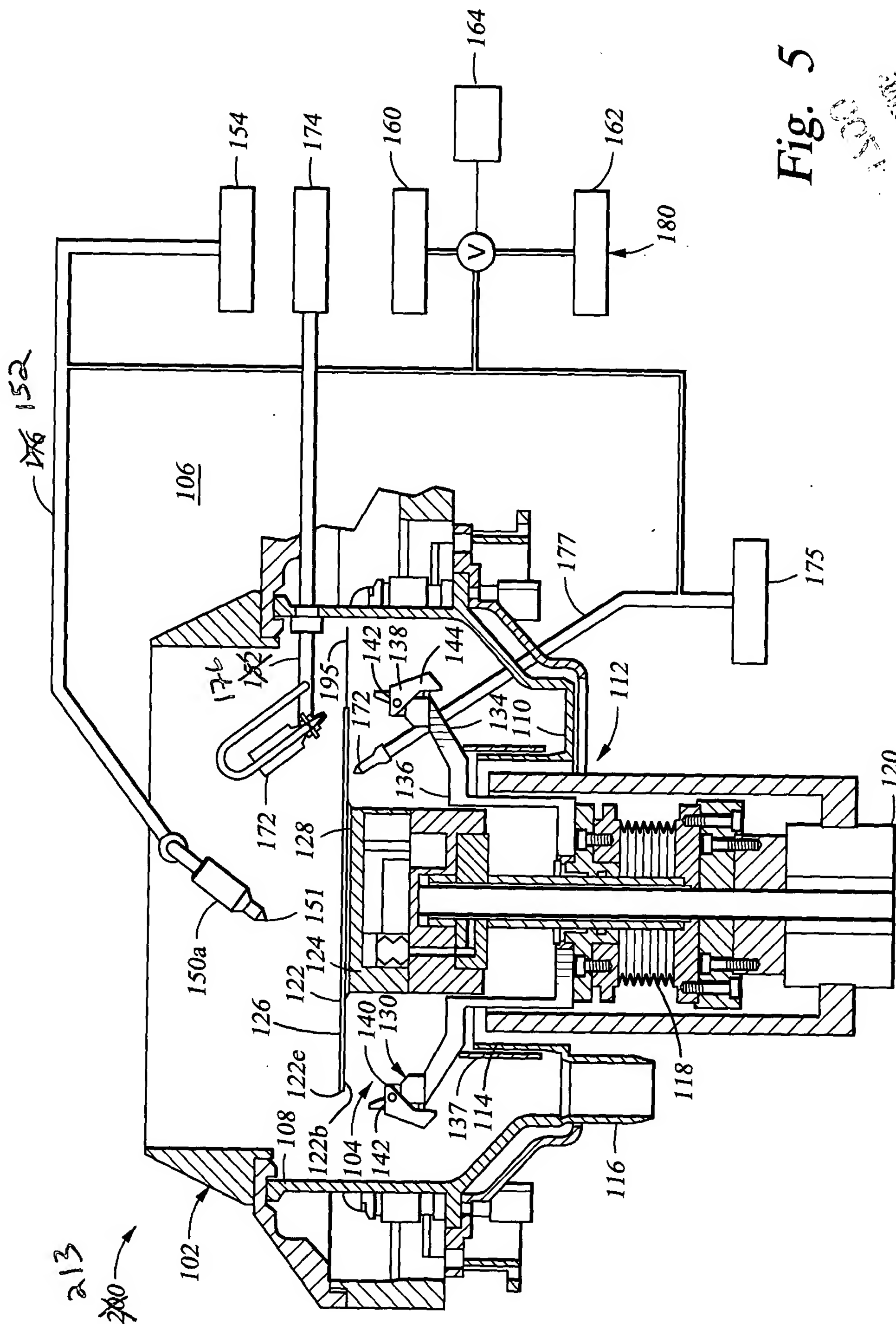


Fig. 5

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FIGURE 7

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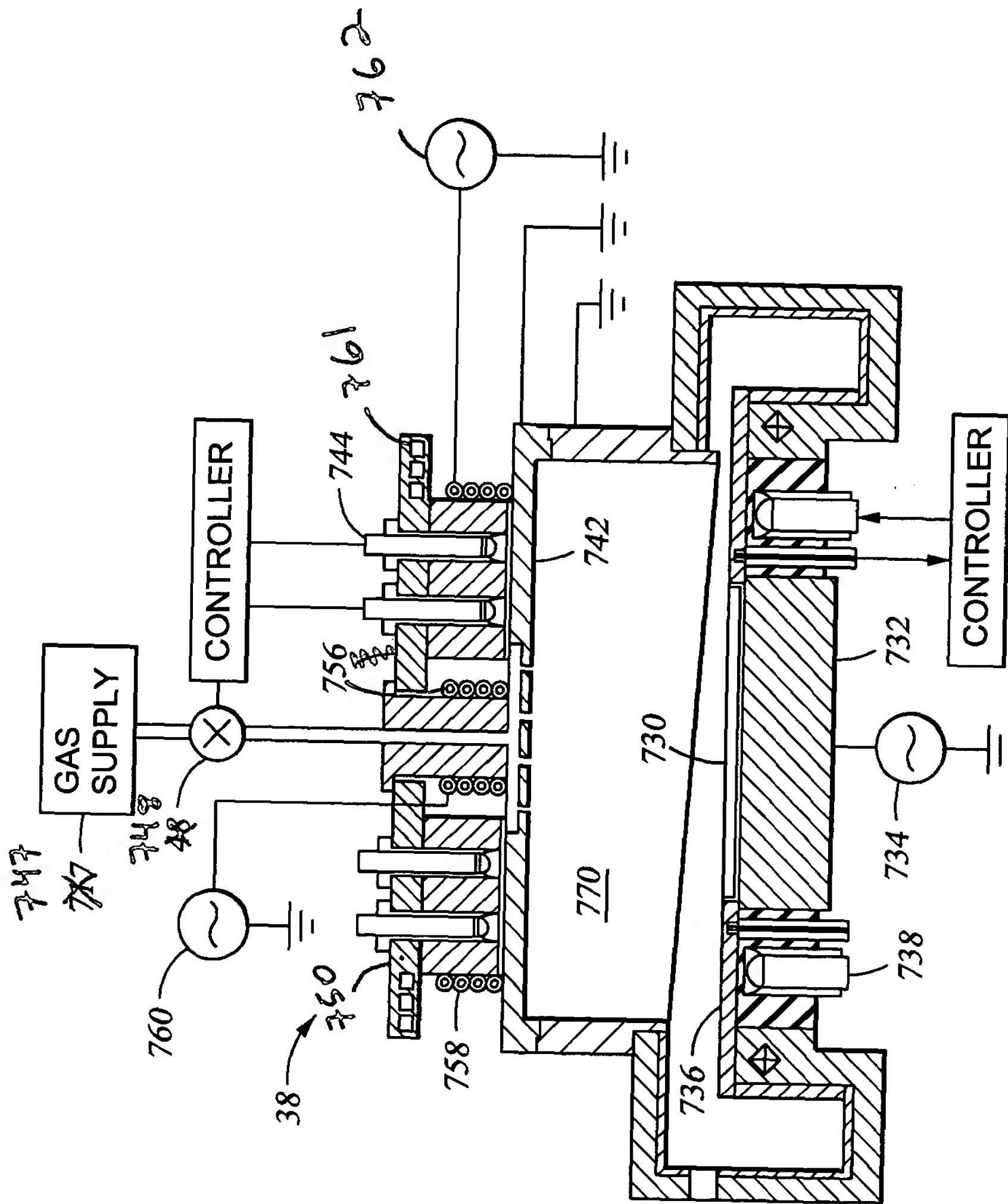


Fig. 7

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SHEET 1 OF 10



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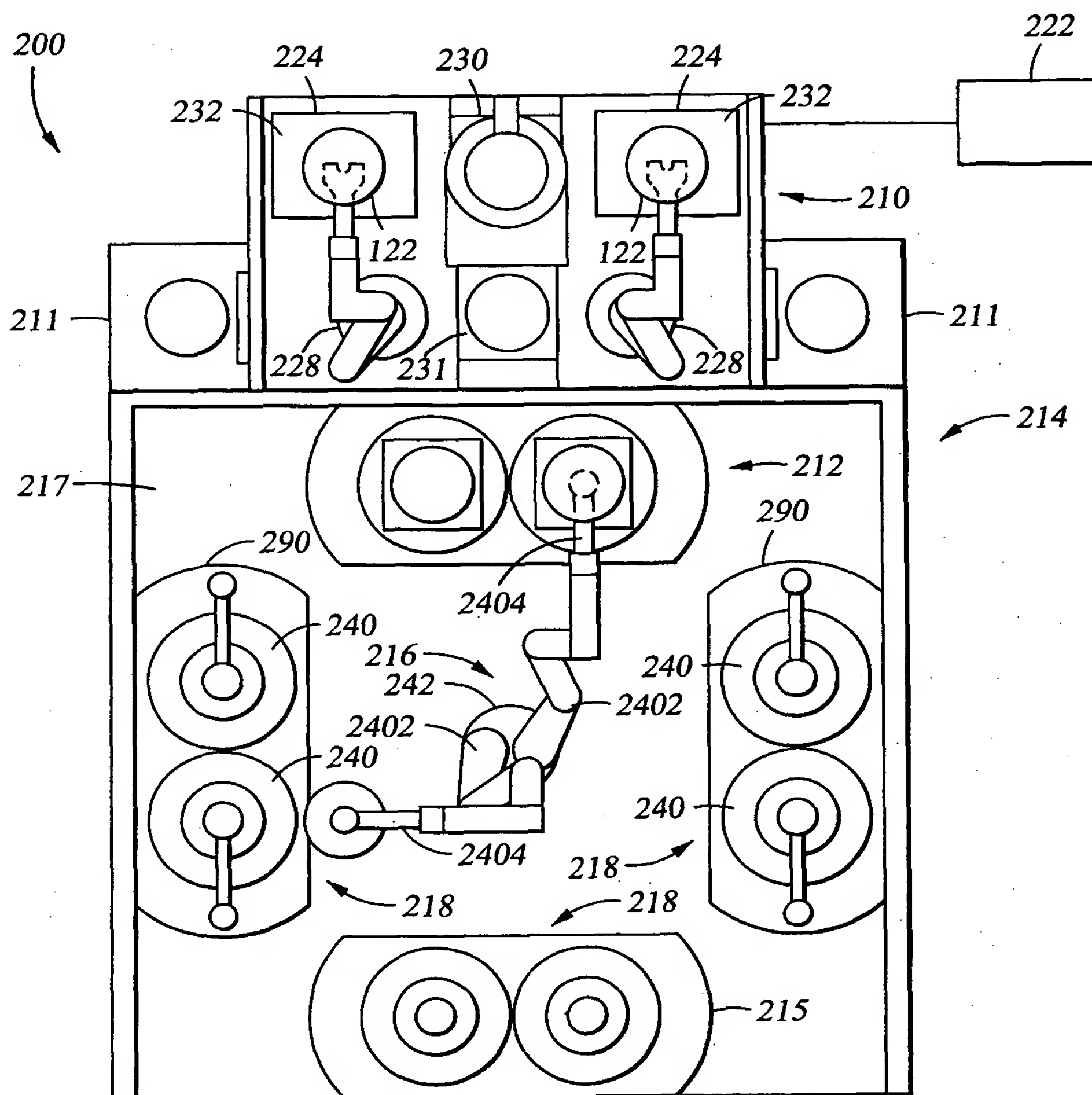


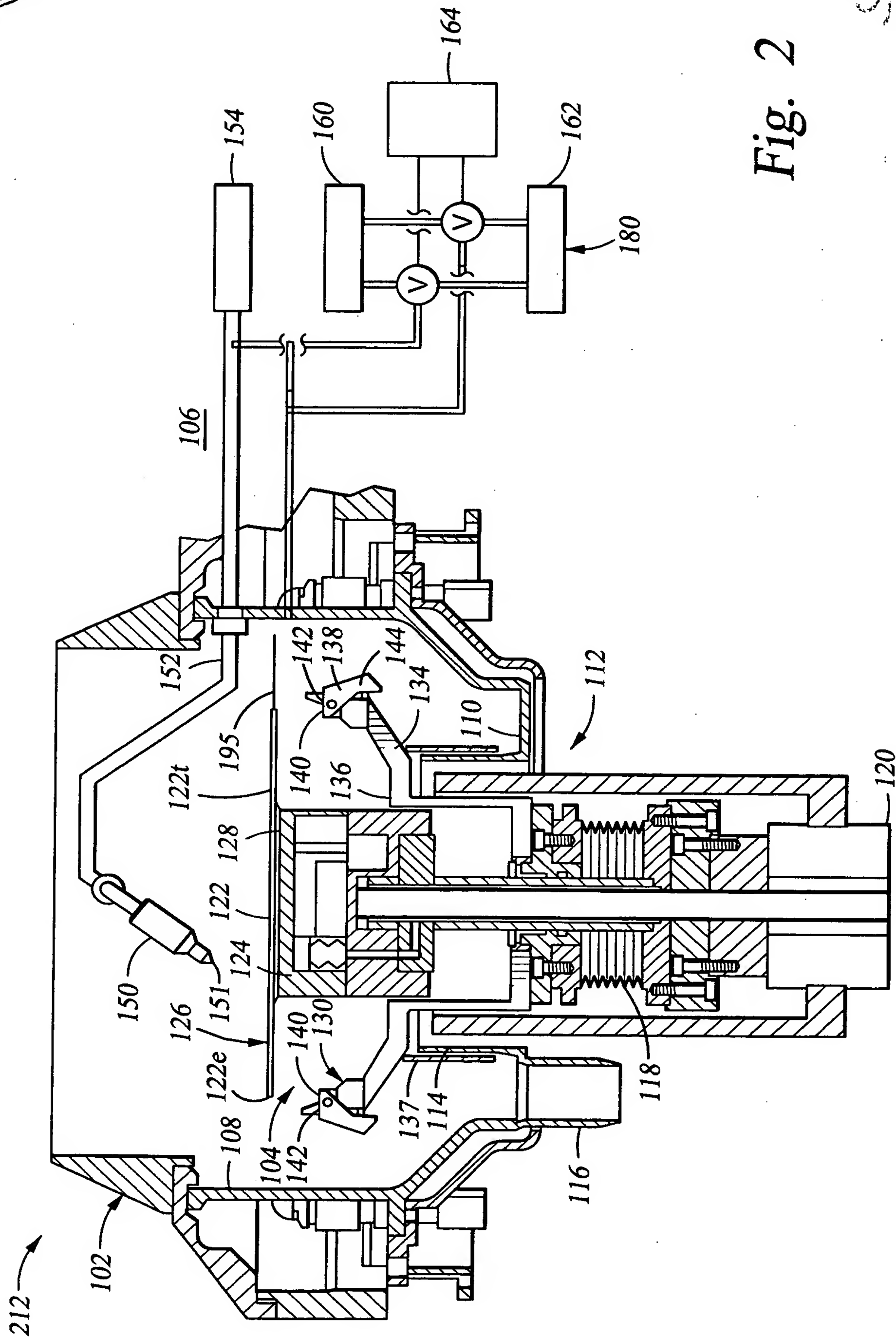
Fig. 1



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Fig. 2



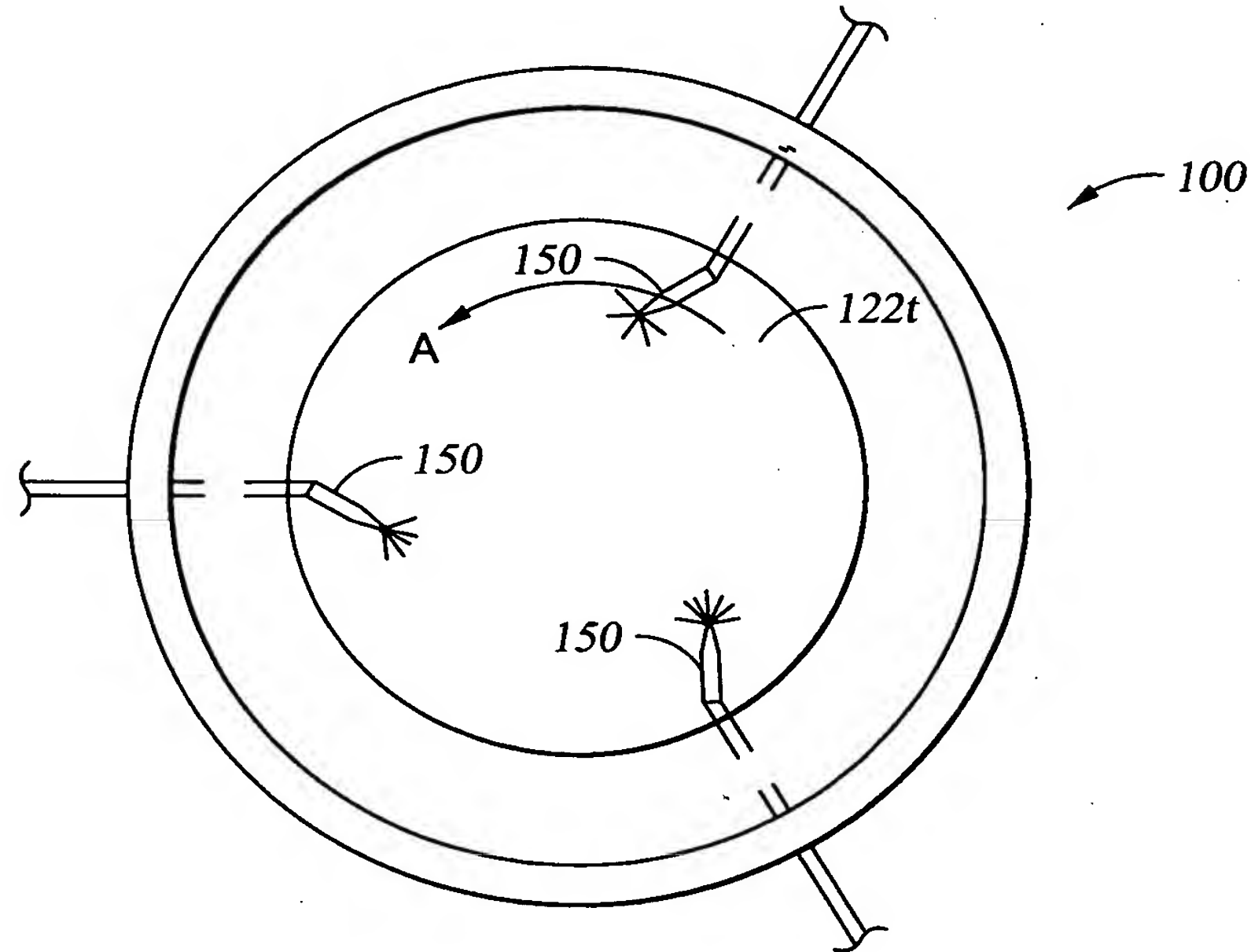


Fig. 3

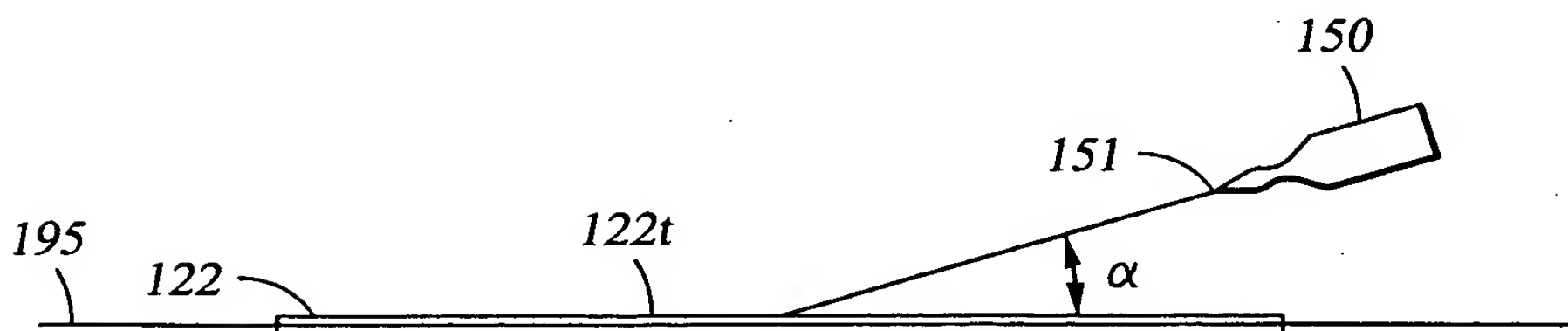


Fig. 4

REPLACEMENT SHEET

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SHEET 5 OF 10



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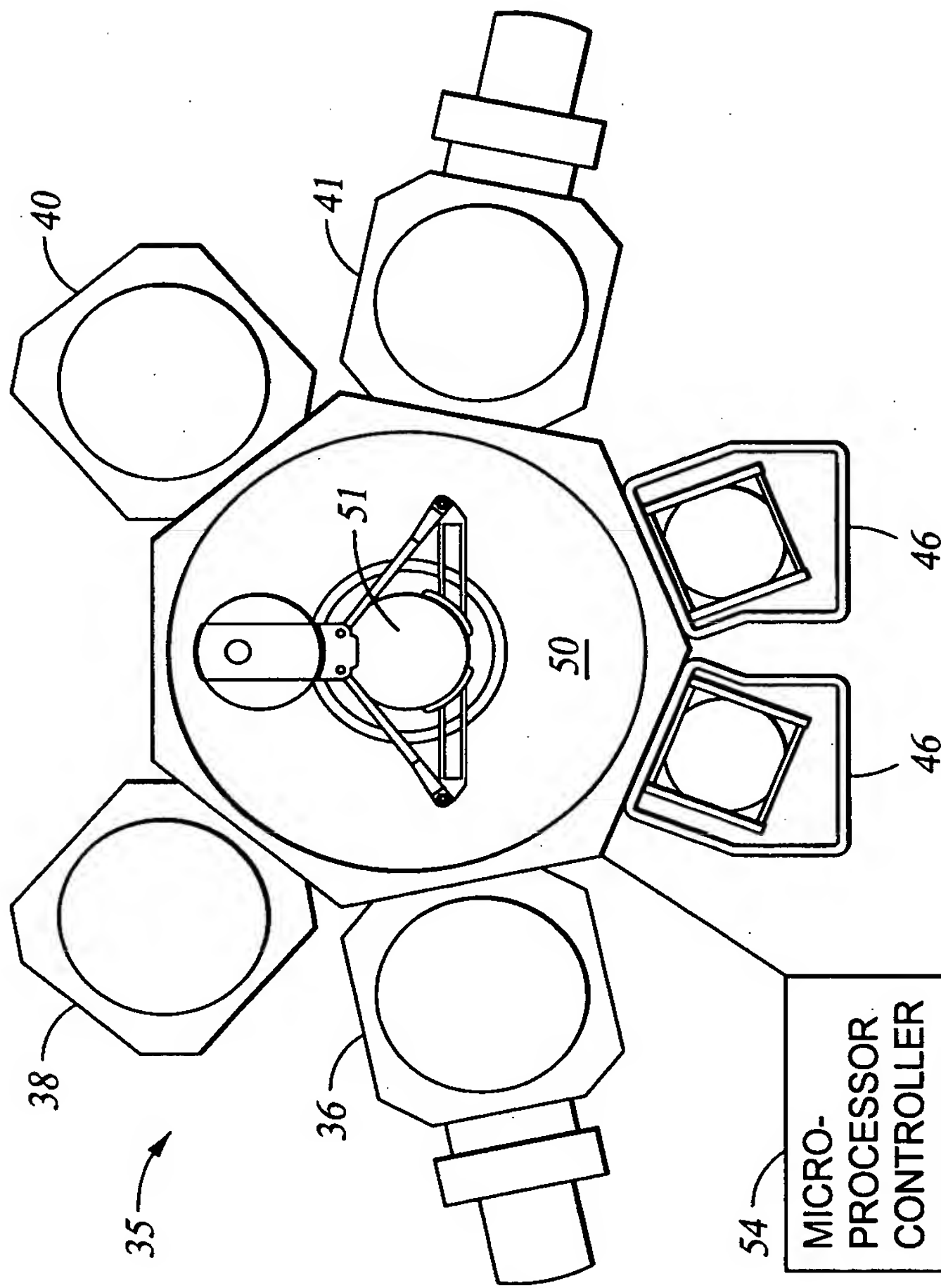


Fig. 6

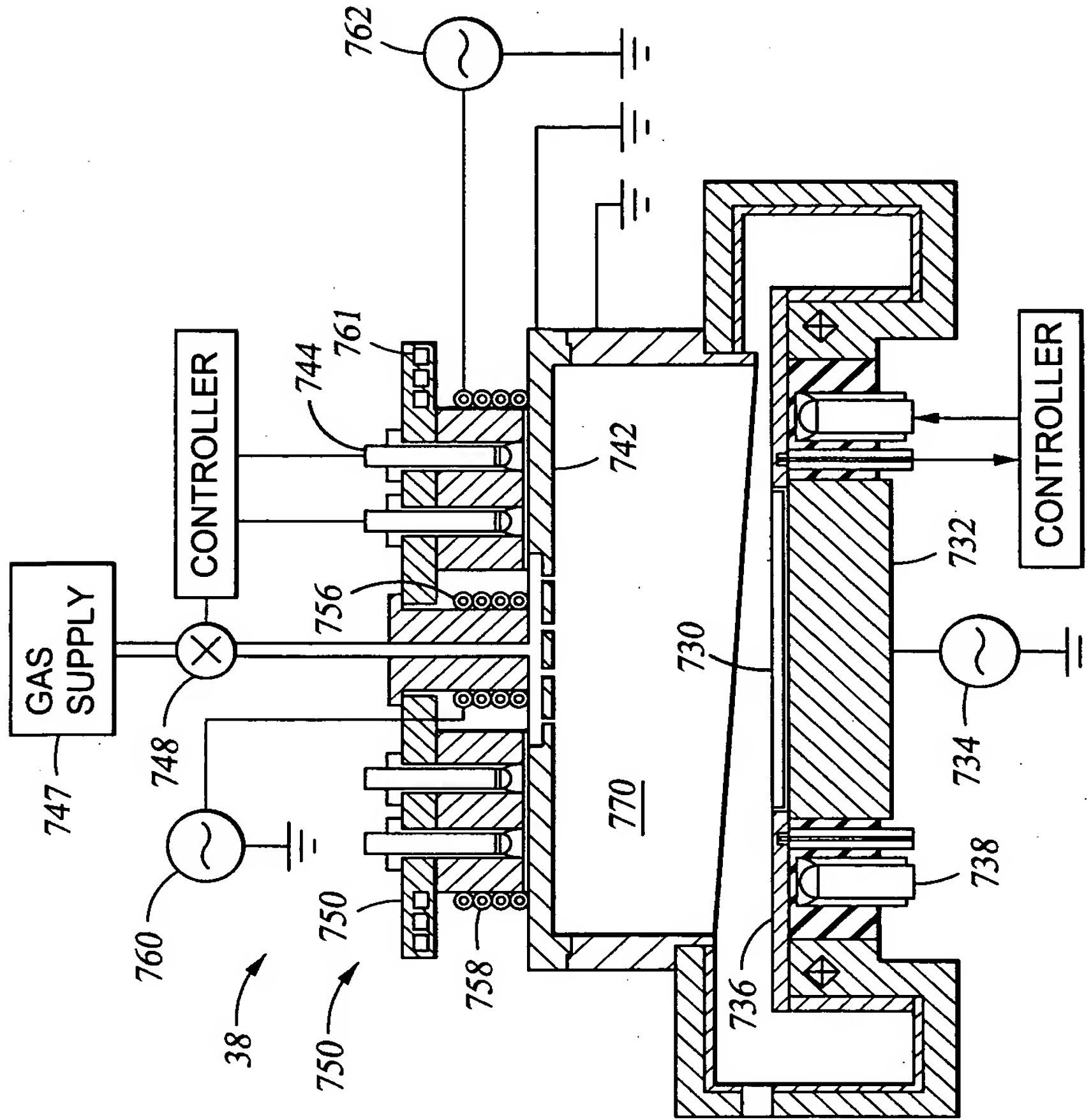


Fig. 7



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SHEET 7 OF 10

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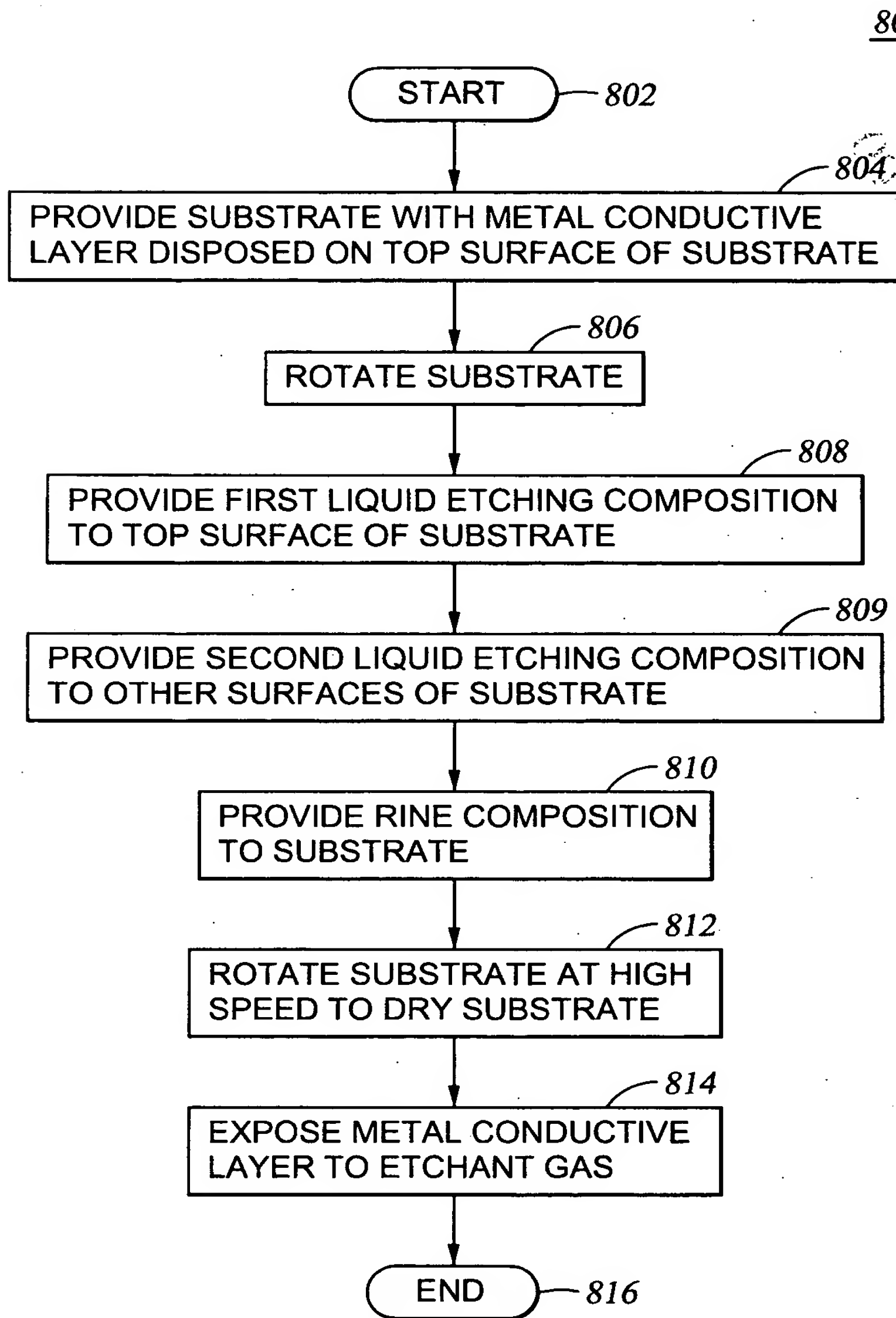


Fig. 8



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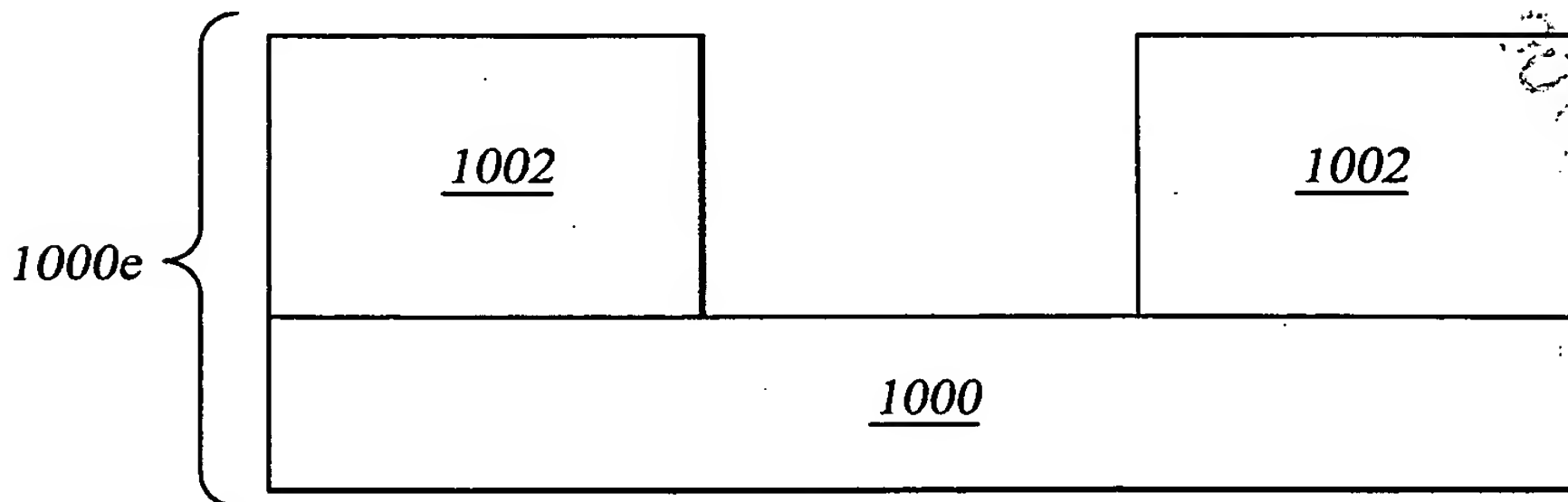


Fig. 10A

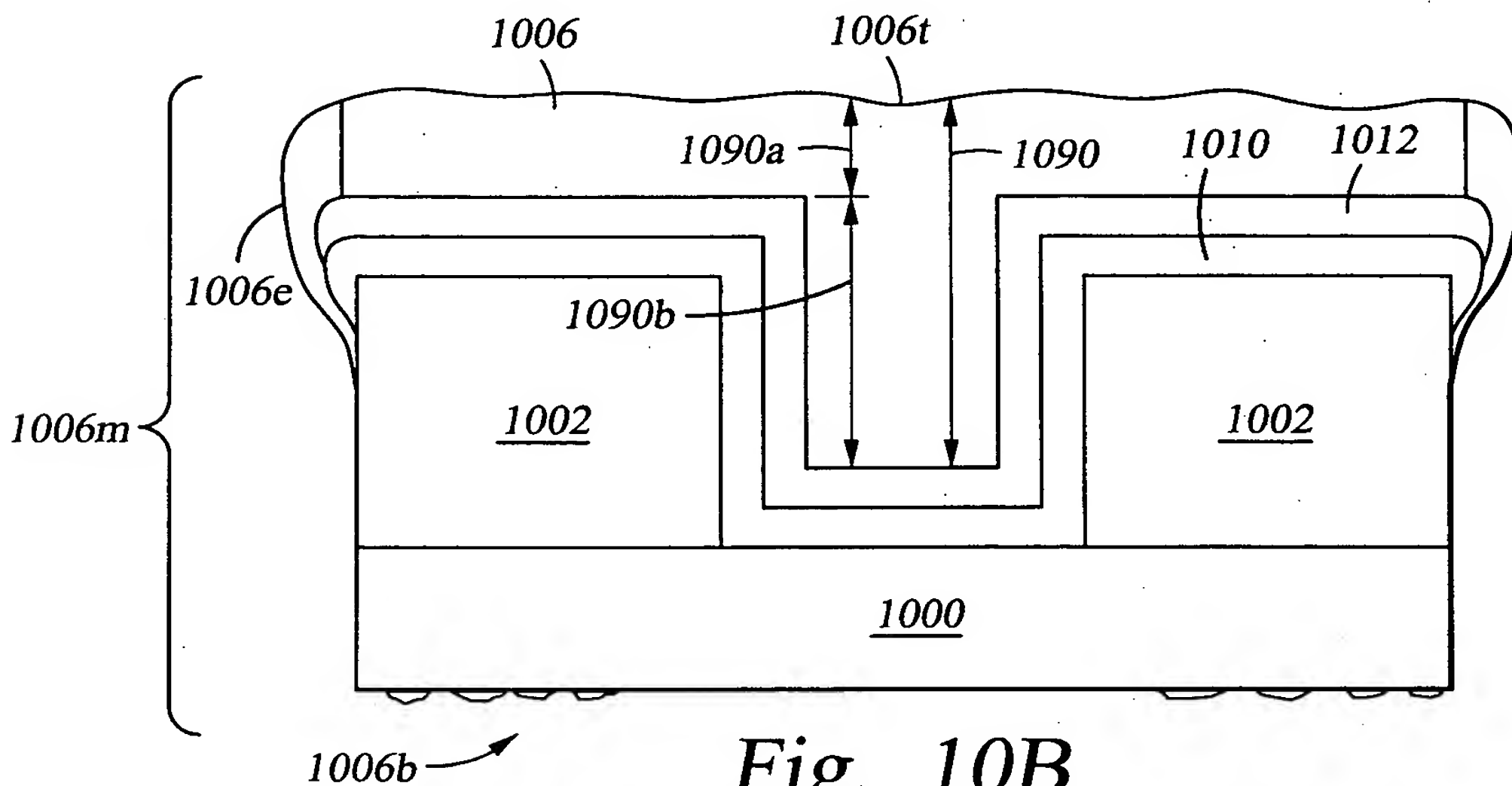


Fig. 10B

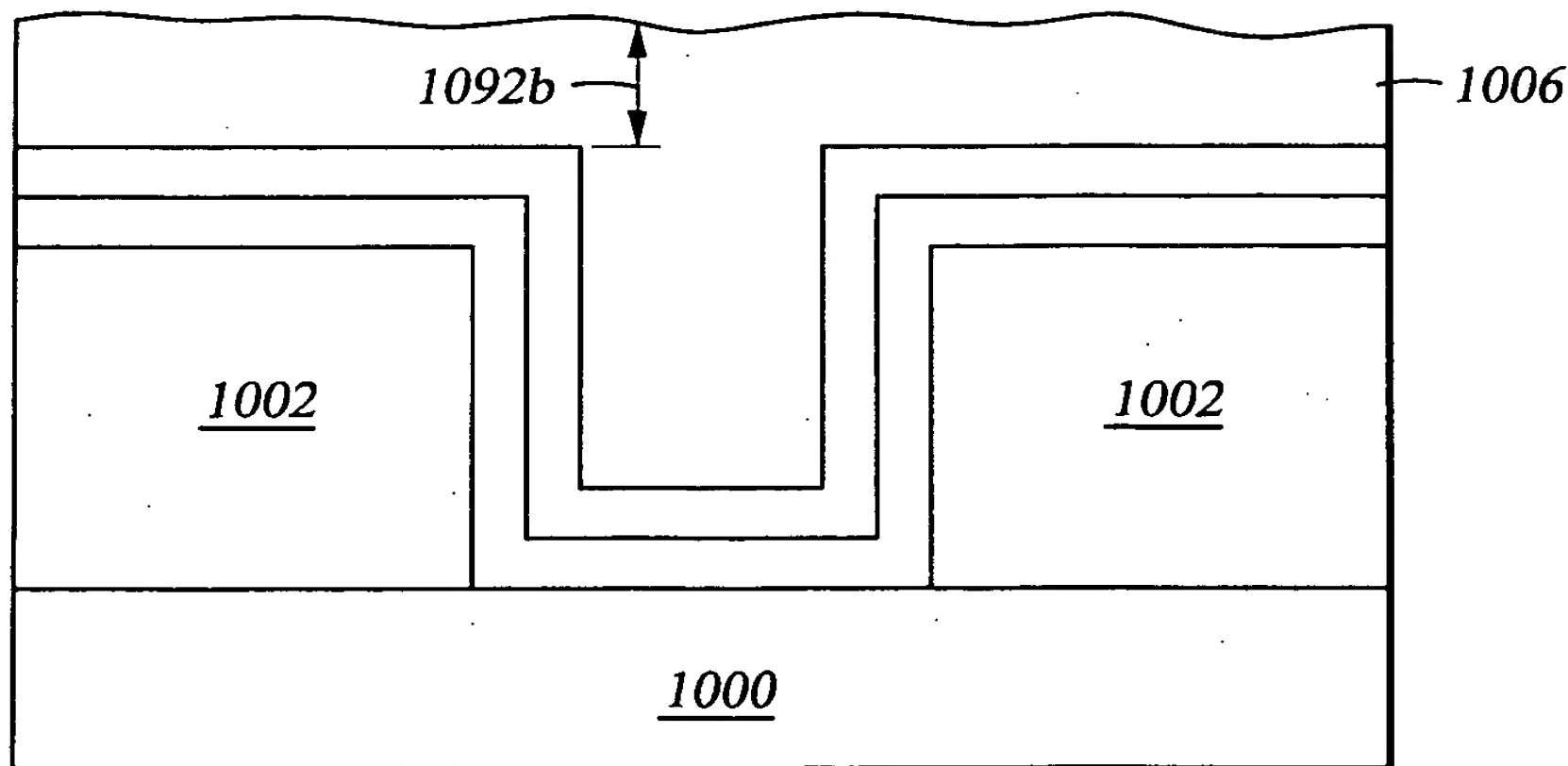


Fig. 10C



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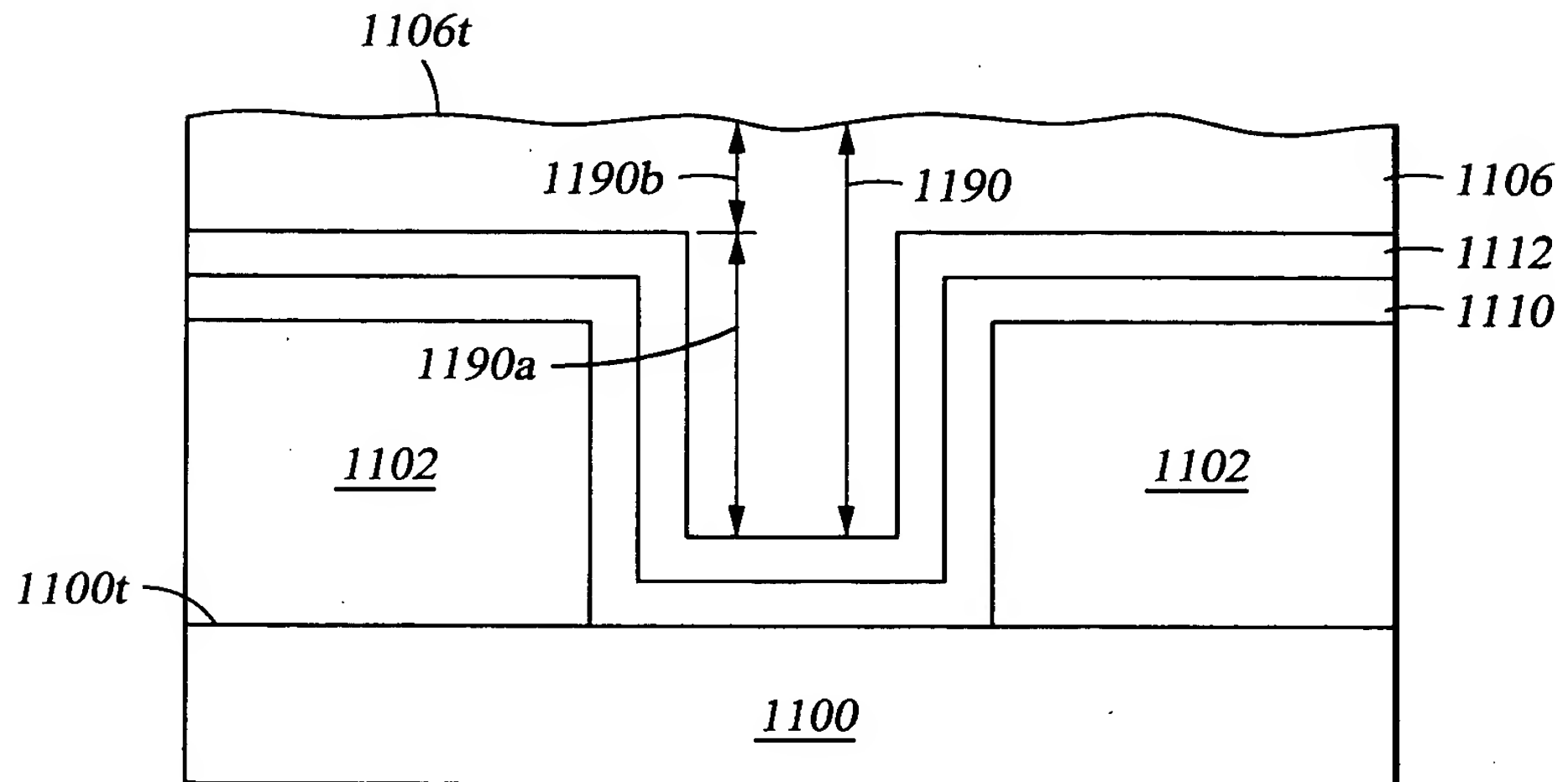


Fig. 11A

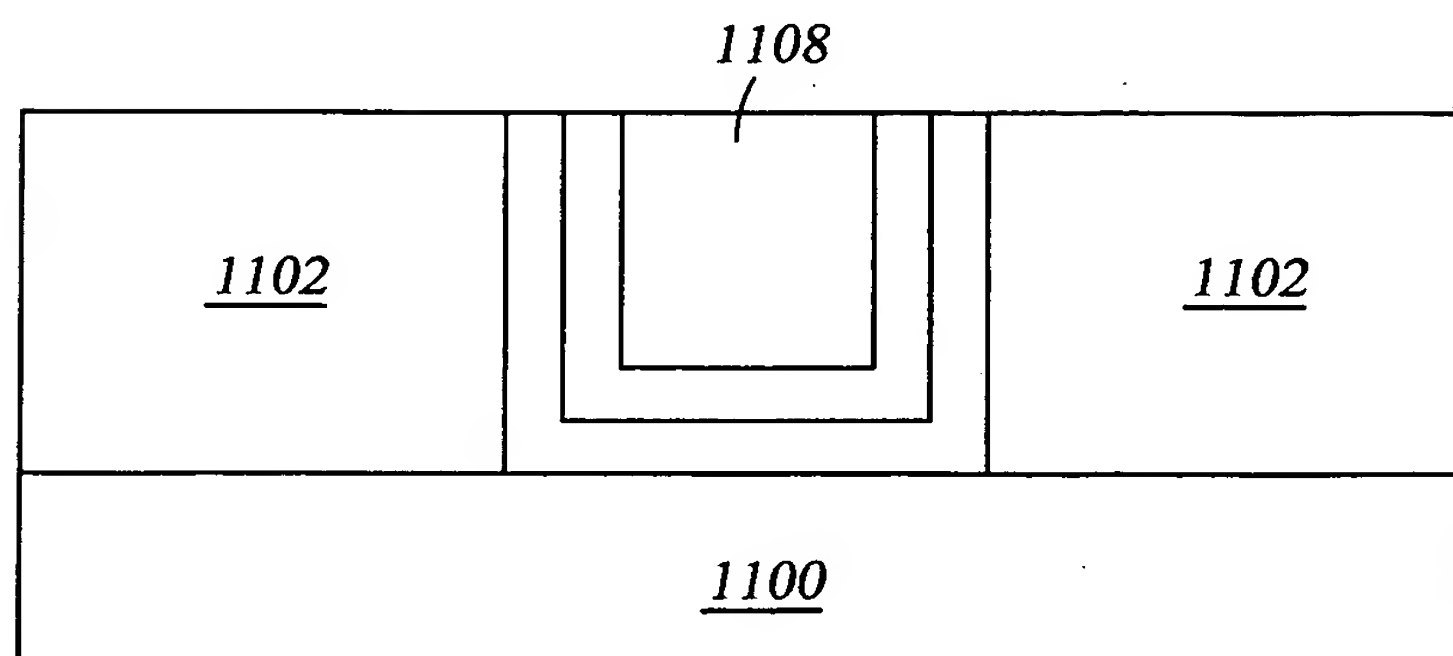


Fig. 11B